Wire Wound Common Mode Choke

■ Features

- SMD construction,and low profile.
- High Impedance and Excelletn Frequency Characteristic.
- Self Electromagnetic Shielding.
- Low Magnetic Flux Leakage.

■ Applications

- LED Light,TV game,Monitor,etc.
- EMI common-mode noise.

■ Product Identification

YPCM □□□□□ — □□□ T

(1) (2) (3) (4)

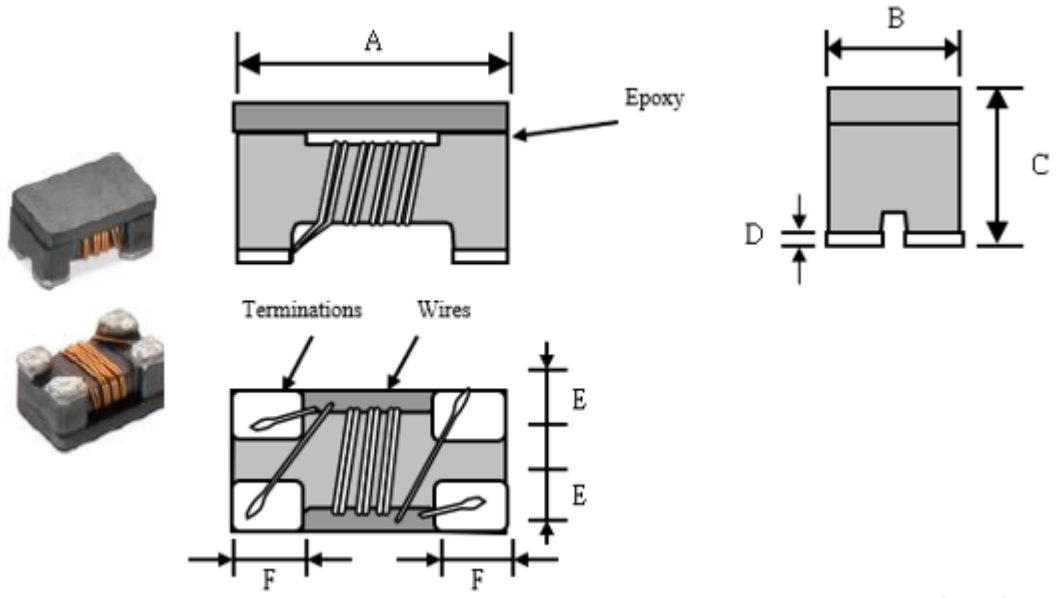
(1)： Type

(2)： Dimensions

(3)： Impedance

(4)： Taping

■ Shapes and Dimensions (Unit：mm)



TYPE	A	B	C	D	E Typ.	F Typ.
YPCM3225A	3.2±0.2	2.5±0.2	1.9±0.2	0.2±0.1	0.80	0.65

■ Electrical Characteristics

Part Number	Z(Ω) Common mode Impedance @100MHz	DCR (Ω) Max.	Rated current Idc(A) Max.	Rated Voltage Vdc (V)Typical	Insulation Resistance IR (MΩ)Min.
YPCM3225A-102T-S2	1000±25%	0.050	1.5	70	10

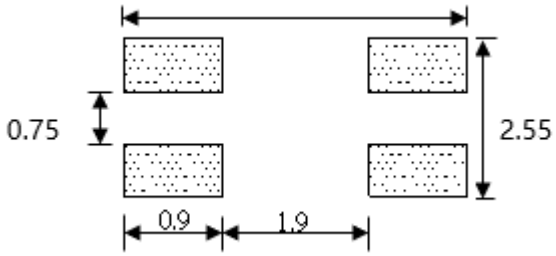
※ Operating Temperature：-40℃ to +85℃

※ Storage Temperature and humidity：-20℃ up to +40℃，75% RH max.

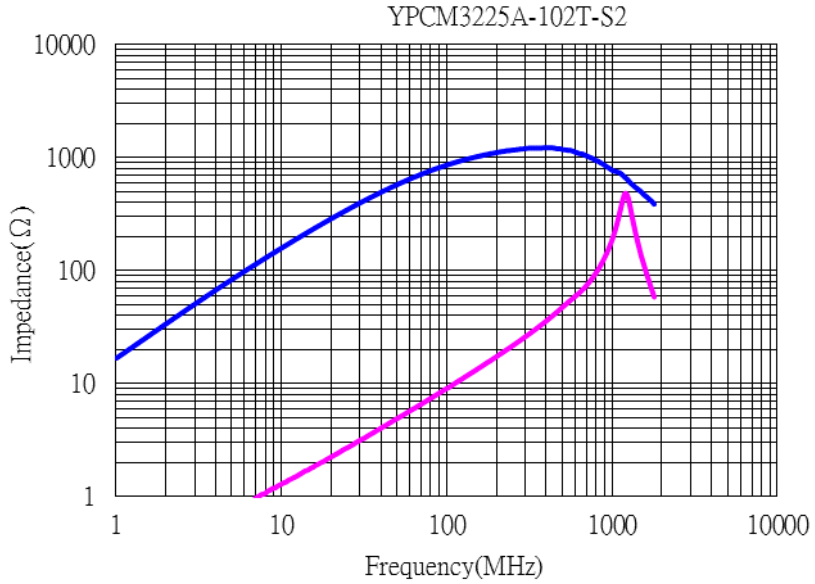
※ Typical Heat Rating DC Current would cause an approximately △T of 40℃

※ If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk.

■ Recommended Footprint(mm)



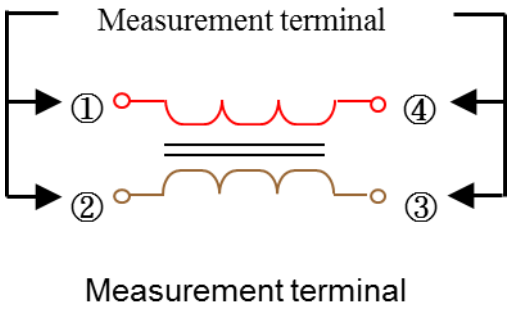
■ Performance Curves



■ Test Equipment

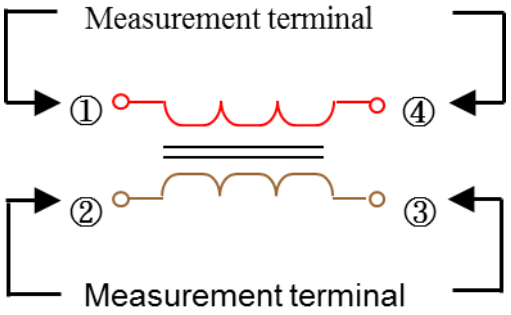
Impedance

Measured by using Agilent 4291A RF Impedance Analyzer.



DC Resistance

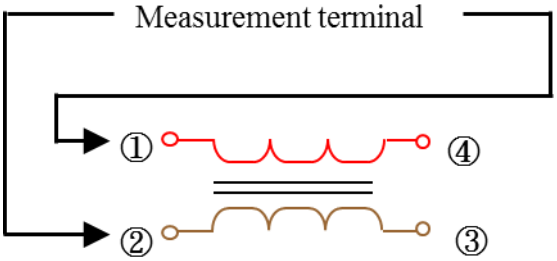
Measured by using Chroma 16502 mill ohm meter.



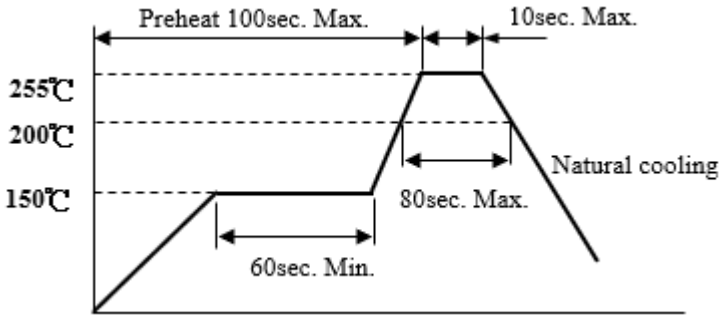
Insulation Resistance

Measured by using Chroma 19073

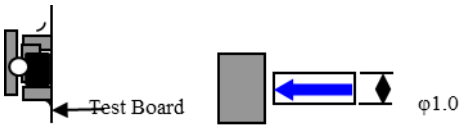
Measurement voltage : 50v ,Measurement time : 60 sec.



■ Recommended Soldering temp.graph



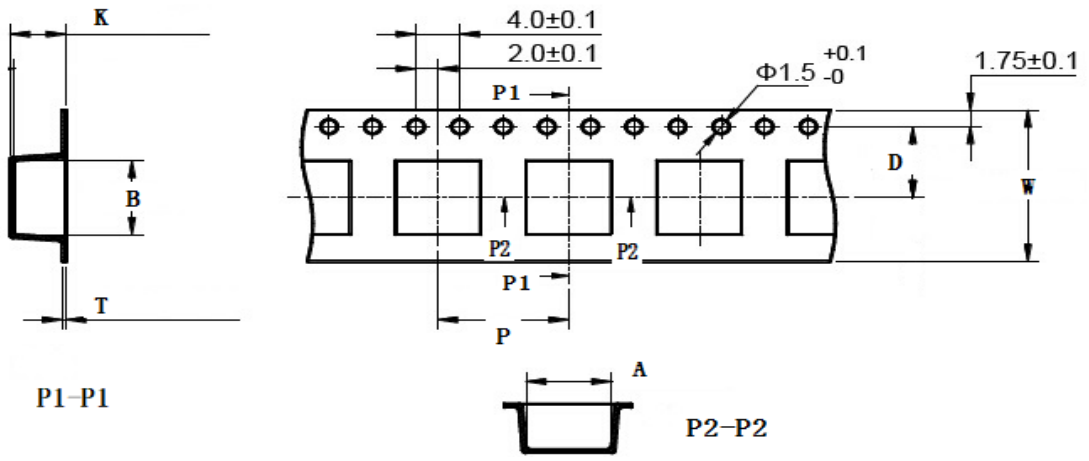
■ Mechanical Reliability

Test	Method Used	Specification & Requirement
Solderability	Solder heat proof: Preheating: 150 ±10℃ 60 seconds Soldering: 245 ±5℃ for 4 ±1 sec	The surface of terminal/pin tested shall be covered with new solder by 90%
Solder Heat Resistance	Preheating:150℃ 60secs Solder temperature: 260±5℃ Flux:rosin Dip time:10±0.5 secs	Components should have not evidence of electrical and mechannical damage Impedance:within ±15% of initial value
Terminal strength	Solder a chip to test substrate and then laterally apply a force in the arrow direction 	<table><tr><th>Series No.</th><th>F（Kg）</th></tr><tr><td>1608</td><td>0.5</td></tr><tr><td>2012</td><td>0.5</td></tr><tr><td>3216</td><td>1.0</td></tr><tr><td>3225</td><td>1.0</td></tr></table>

■ Endurance Reliability

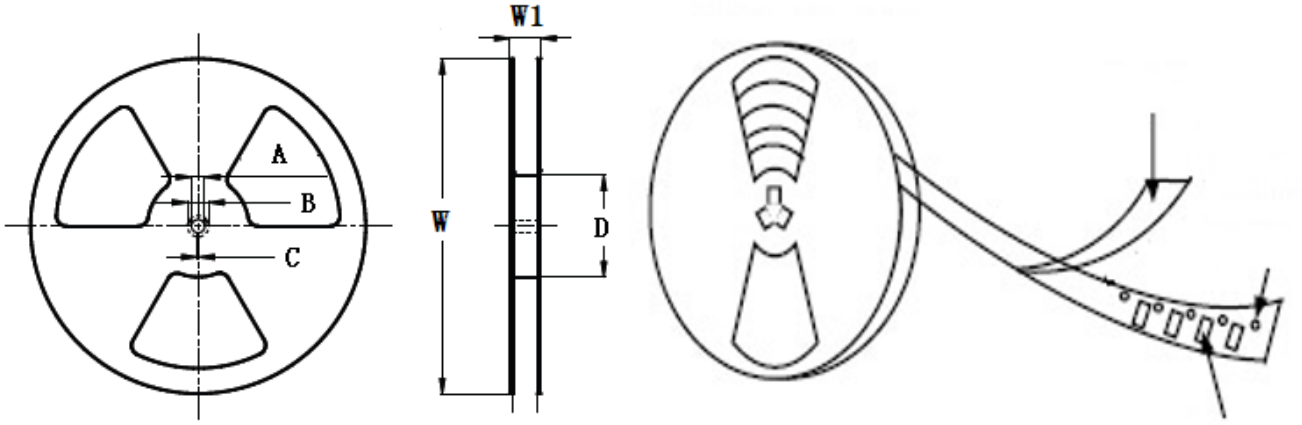
Test	Method Used	Specification & Requirement
Thermal Shock Test	-65℃, (30 mins) -> room temp. (2 mins) -> 125℃, (30 mins) -> room temp. (2 mins) 50 cycles	Impedance change within ± 15% Without mechanical damage
High Temperature Exposure	Apply IDC current @ 60℃ ambient Humidity: 90% Duration: 168 hrs	Impedance change within ± 15% Without mechanical damage
Low Temp. Storing	Storing Temp. -40 ±2 ℃ for total 168 +5/-0 hours	Impedance change within ± 15% Without mechanical damage
High Temp. Storing	Storing Temp. 125 ±2 ℃ for total 168 +5/-0 hours	Impedance change within ± 15% Without mechanical damage

■ Taping Dimensions(Unit:mm)



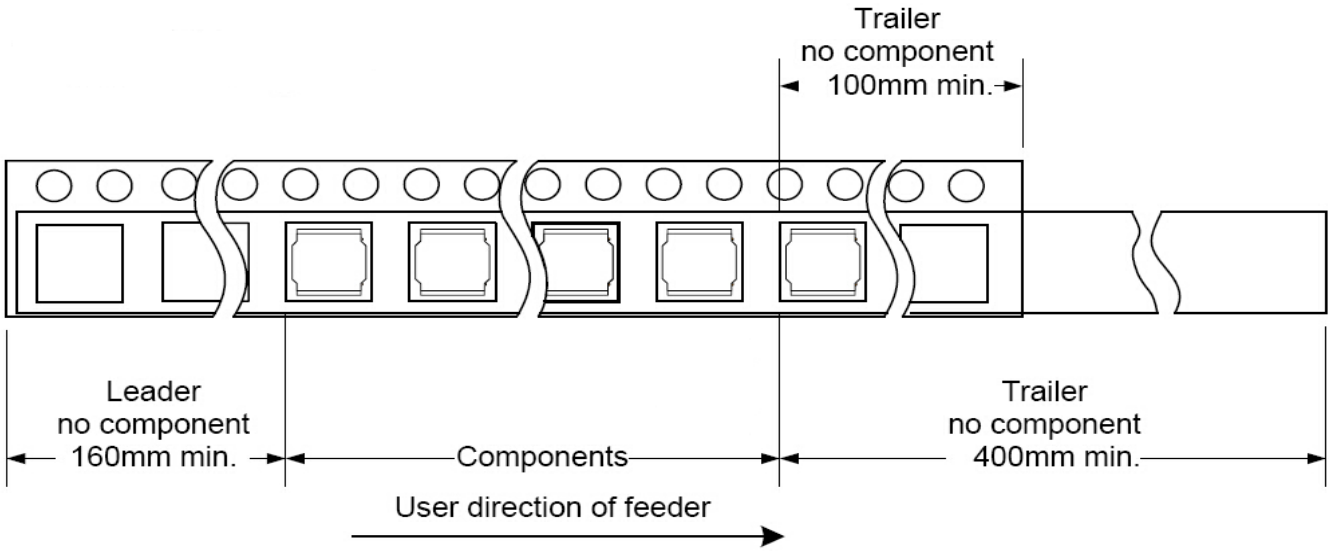
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YPCM3225A	8.00	2.80	3.60	3.50	4.00	2.30	0.25	1000

■ Reel Dimensions(Unit:mm)

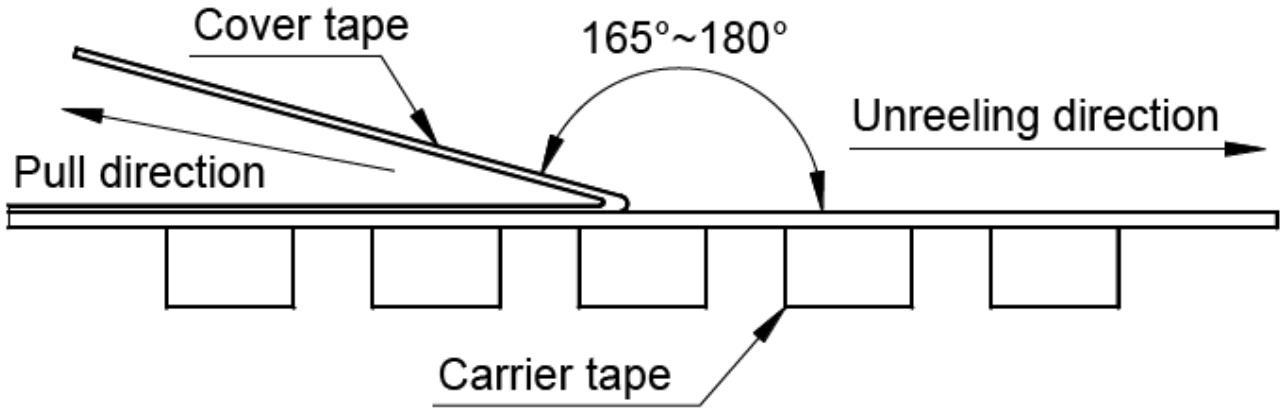


TYPE	W	W1	A	B	C	D
YPCM3225A	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.

Unikeyic Electronics

Global Electronic Components Distributor

Click to view pricing, inventory, delivery, and lifecycle information:

YJYCOIN:

CD75YP0705-102M YLM1211-202T YLM1211-222T YSPIA1770-100M YDFW1515T-302L03015 YNR6045-330M YP0402-330M YPRH1209-470M YSPI0630A-1R0M CD54YP0504-101M YAL0204-151K YI201209U800-6R0T YNR4030-6R8M YPRH1207-4R7M YSMC2016S-R24M YI100505U121-1R2T YI321611U601-3R0T YLCM0904-471T YSFP2915S-6R8M YSPIA1770-101M CD32YP0302-4R7M YWLD2012-3R3K YNR1050-271M YNR2016-3R3M YP0705-680M YPRH1207-150M YSPI0730-R22M YSPI1050-101M YLM2012-900T YPRH3D16-330M